

100V N-Channel Enhancement Mode MOSFET

Description

The SX70N10T uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 100V I_{D} = 70A$

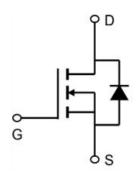
 $R_{DS(ON)}$ < 25m Ω @ Vgs=10V

Application

Automative lighting

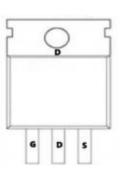
Load switch

Uninterruptible power supply









Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	100	V	
VGS	Gate-Source Voltage	±20	V	
lo@Tc=25℃	Drain Current, Vos @ 10V	70	Α	
lo@Tc=100°C	Drain Current, Vos @ 10V	56	А	
IDM	Pulsed Drain Current ¹	210	А	
EAS	Single Pulse Avalanche Energy	110	mJ	
P o@T c= 25 °C	Total Power Dissipation	90	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
RθJA	Maximum Thermal Resistance, Junctionambient	62.5	°C/W	
RθJC	Maximum Thermal Resistance, Junction-case	1.4	°C/W	



100V N-Channel Enhancement Mode MOSFET



Electrical Characteristics@Ti=25°C(unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Ib=250uA	100	110		V
RDS(ON)	Static Drain-Source On-Resistance ²	Vgs=10V , Ip=30A		18	25	mΩ
VGS(th)	Gate Threshold Voltage	Vgs=Vps , Ip =250uA	2.0	3.0	4.0	V
	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25℃			1	uA
IDSS		V _{DS} =80V , V _{GS} =0V , T _J =55℃			5	
IGSS	Gate-Source Leakage Current	Vgs=±20V , Vps=0V			±100	nA
gfs	Forward Transconductance	Vps=5V , Ip=30A		31		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.9	3.8	Ω
Qg	Total Gate Charge (10V)			27.6		
Qgs	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =30A		11.4		nC
Qgd	Gate-Drain Charge			7.9		
Td(on)	Turn-On Delay Time			16.5		
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V		35		ns
Td(off)	Turn-Off Delay Time	, R _G =3.3Ω, I _D =30A		17.5		
Tf	Fall Time			12		
Ciss	Input Capacitance			1890		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		268		pF
Crss	Reverse Transfer Capacitance			67		
IS	Continuous Source Current ^{1,5}				58	Α
ISM	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			130	Α
VSD	Diode Forward Voltage ²	Vgs=0V,Is=1A,TJ=25℃			1.2	V
trr	Reverse Recovery Time			22		nS
Qrr	Reverse Recovery Charge	lF=30A , dl/dt=100A/μs , Tյ=25℃		20		nC
1				1		

Note:

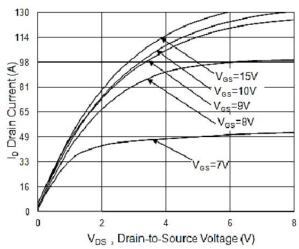
- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2 . The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3 、The EAS data shows Max. rating . The test condition is VDD=72V,VGS=10V,L=0.1mH,IAS=40A
- 4 . The power dissipation is limited by 150 $\!\!\!^{\circ}\!\!\!^{\circ}$ junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.

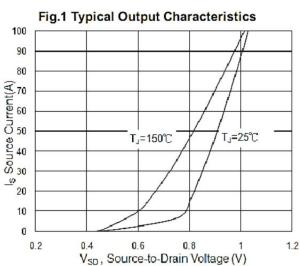
2

www.sxsemi.com



Typical Characteristics





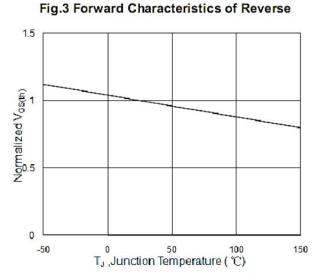
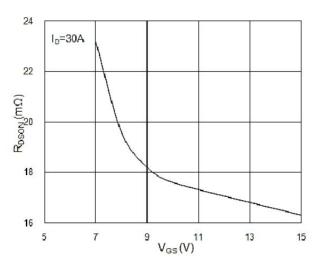
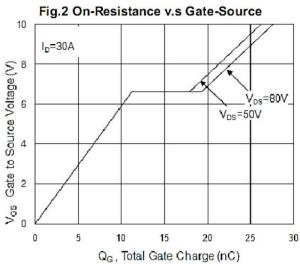


Fig.5 Normalized V_{GS(th)} vs. T_J





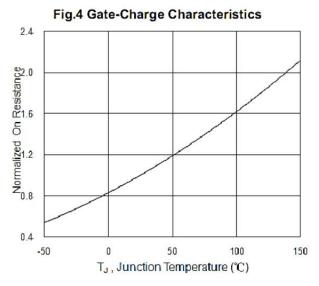
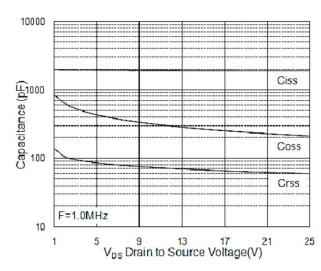


Fig.6 Normalized RDSON vs. TJ

www.sxsemi.com



Typical Characteristics



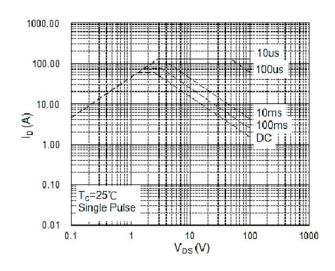


Fig.7 Capacitance

Fig.8 Safe Operating Area

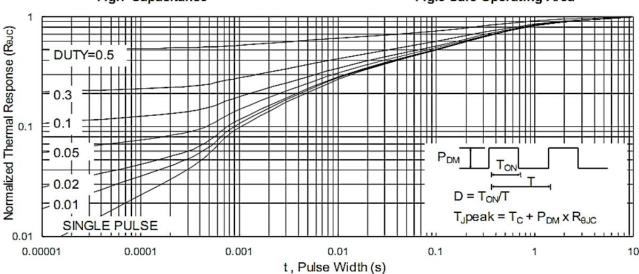


Fig.9 Normalized Maximum Transient Thermal Impedance

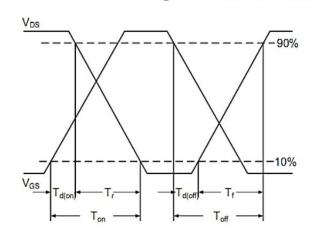


Fig.10 Switching Time Waveform

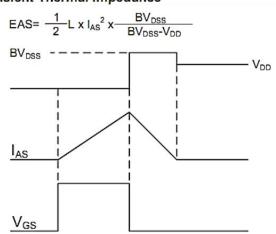
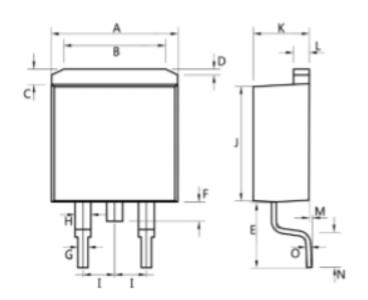


Fig.11 Unclamped Inductive Switching Waveform



100V N-Channel Enhancement Mode MOSFET

Package Mechanical Data- TO-263-3L



Dim.	Min.	Max.		
Α	10.0	10. 5		
В	7.25	7.75		
С	1.3	1.5		
D	0.55	0.75		
E	5.0	6.0		
F	1.4	1.6		
G	0.75	0.95		
Н	1.15	1.35		
I	Typ 2.54			
J	8.4	8.6		
K	4.4	4.6		
L	1.25	1.45		
M	0.02	0.1		
N	2.4	2.8		
0	0.35	0.45		
All Dimensions in millimeter				

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800

5